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**Amendments to the Claims:**

This listing of claims will replace all previous versions, and listings, of claims in the application.

**Listing of Claims:**

1. (currently amended) A polishing pad comprising a body having (a) a top surface comprising a first set of grooves with a first depth and first width and (b) a bottom surface comprising a second set of grooves with a second depth and second width, wherein the first set of grooves and second set of grooves are interconnected and are oriented such that they are not aligned, and wherein the polishing pad has a void volume of about 30% or more.
2. (original) The polishing pad of claim 1, wherein the first and second sets of grooves have a cross-sectional shape selected from the group consisting of lines, curves, circles, ovals, squares, rectangles, triangles, diamonds, and combinations thereof.
3. (original) The polishing pad of claim 2, wherein the grooves are linear grooves.
4. (original) The polishing pad of claim 3, wherein the first and second sets of grooves are non-parallel.
5. (canceled)
6. (currently amended) The polishing pad of claim ~~[[5]]~~ 1, wherein the polishing pad has a void volume of about 70% or more.
7. (original) The polishing pad of claim 1, wherein the first set of grooves is rotated by an angle of about 10° to about 90° relative to the second set of grooves.
8. (original) The polishing pad of claim 7, wherein the angle is about 90°.

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9. (original) The polishing pad of claim 1, wherein a first depth of the first set of grooves and a second depth of the second set of grooves combine to have a total groove depth that is about equal to or greater than the thickness of the polishing pad.
10. (original) The polishing pad of claim 9, wherein the first set of grooves and second set of grooves are interconnected by primary channels that are oriented perpendicular to the top surface of the polishing pad.
11. (withdrawn) The polishing pad of claim 10, further comprising a plurality of secondary channels extending through the thickness of the polishing pad.
- 12.-13.(canceled)
14. (original) The polishing pad of claim 1, wherein the first set of grooves, the second set of grooves, or a combination thereof have an average groove width of about 0.1 mm to about 2 mm.
15. (canceled)
16. (original) The polishing pad of claim 1, wherein the body comprises a polymer resin selected from the group consisting of thermoplastic elastomers, thermoplastic polyurethanes, thermoplastic polyolefins, polycarbonates, polyvinylalcohols, nylons, elastomeric rubbers, elastomeric polyethylenes, polytetrafluoroethylenes, polyethyleneterephthalates, polyimides, polyaramides, polyarylenes, polyacrylates, polystyrenes, polymethylmethacrylates, copolymers thereof, and mixtures thereof.
17. (original) The polishing pad of claim 16, wherein the polymer resin is a thermoplastic polyurethane resin.
18. (original)The polishing pad of claim 1, wherein the body of the polishing pad further comprises abrasive particles.
19. (currently amended) The polishing pad of claim 1, wherein the body of the polishing pad is conductive.

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20. (canceled)

21. (original) The polishing pad of claim 19, wherein the body of the polishing pad further comprises a conductive polymer.

22.-26. (canceled)

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